

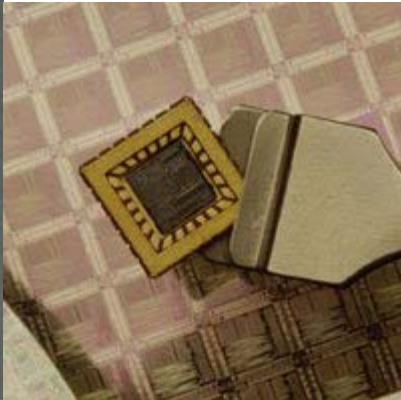
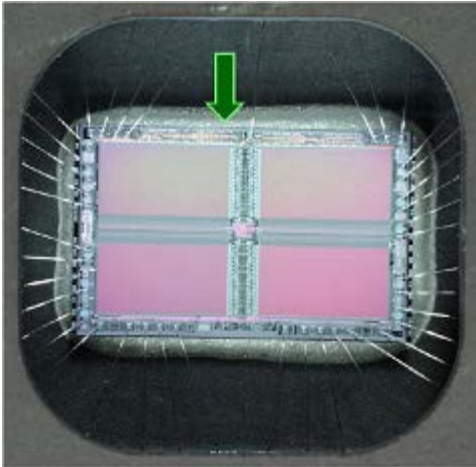
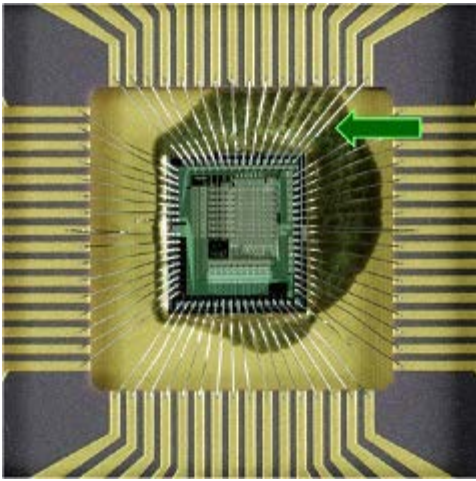
Other Specialty Film Die-Attach and Die Bonding Film Adhesive Applications:

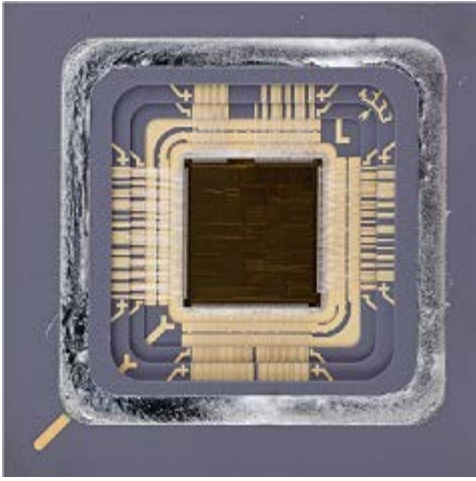
Die-attach film adhesives (die-bonding film adhesives) are not for making memory devices only. AIT conductive die-attach film adhesive are now used in some of the more powerful devices with 20 micron thick silver filled DAF.

AI Technology, Inc. is one of the first manufacturers of die-attach film adhesive that have proven capability and technology to make 10 micron thick DAF for 450mm wafer.

1. Screen-printable rapid-curing die-attach film (DAF):

- Screen-printable
- Tacks at 80-150°C in seconds with minimal pressure of 4-8 psi with rapid curing and without pressure at select temperatures
- Alternative inline tack-and-curing at 250°C within seconds
- Maintain more than 300 psi bond strength @ 250°C for fast wire-bonding
- Molecularly engineered for low moisture absorption and high temperature stability
- Designed for dies less than 1 cm
- Examples: LESP7670-WL, LESP8680-WL





Die-attach film (DAF) adhesive helps to eliminate the bleeding issues when paste die-attach adhesive is used.

Die-attach film adhesive can provide much better control in bondline thickness.

2. Ultra-high thermally conductive die-attach pastes:

- Proven for military electronics and thermal performance
- Molecularly engineered for high temperature stability
- Designed for large and small dies
- Examples: ME8456-DA, ME8650-RCT

Stack-chip packaging are more efficient and more reliable with the use of die-attach film adhesives with electrical conductive or insulating requirements.